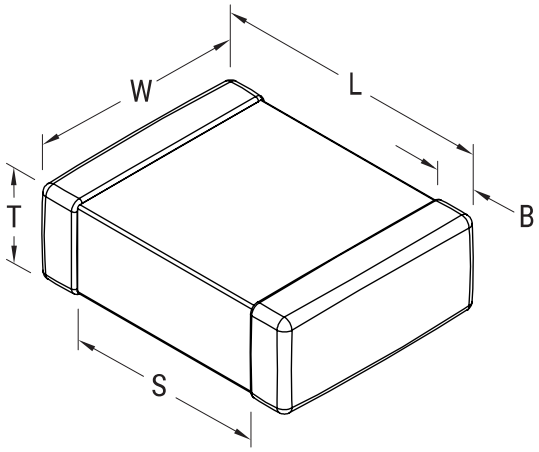
C0805C102FAGEC

ESD SMD Comm C0G, Ceramic, 1,000 pF, 1%, 250 VDC, C0G, SMD, MLCC, Temperature Stable, Electro Static Discharge, Class I, 0805



Click here for the 3D model.

General Information	
Series	ESD SMD Comm C0G
Style	SMD Chip
Description	SMD, MLCC, Temperature Stable, Electro Static Discharge, Class I
Features	Temperature Stable, Low ESR, Class I
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Typical Component Weight	13 mg
Shelf Life	78 Weeks
MSL	1

Dimensions	
Chip Size	0805
L	2mm +/-0.2mm
W	1.25mm +/-0.2mm
T	0.9mm +/-0.10mm
S	0.7mm MIN
B	0.5mm +/-0.25mm

Packaging Specifications	
Packaging	Bulk, Bag
Packaging Quantity	1

Specifications	
Capacitance	1,000 pF
Measurement Condition	1 MHz 1.0Vrms
Capacitance Tolerance	1%
Voltage DC	250 VDC
ESD Level per AEC-Q200	8,000 V ESD Level
Dielectric Withstanding Voltage	625 VDC
Temperature Range	-55/+125°C
Temperature Coefficient	C0G
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1MegaHz 1.0Vrms
Dissipation Factor	0.1% 1 MHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	100 GOhms

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